

# Highly Versatile, Regulated Single-Output, Buck-Boost Ambient Energy Manager For AC/DC Sources with Optional Primary Battery

#### **Features**

Ultra-low power start-up

- Cold start from 275 mV input voltage and 3  $\mu$ W input power (typical)

#### Very efficient energy extraction

- Open-circuit voltage sensing for Maximum Power Point Tracking (MPPT)
- Selectable open-circuit voltage ratios from 35% to 80% or fixed impedance
- Programmable MPPT sensing period
- MPPT voltage operation range from 100 mV to 4.5 V

# Adaptive and smart energy management with optional primary battery

- Switches automatically between boost, buck-boost and buck operation, to maximize energy transfer from its input to the output
- Automatically selects between the source, storage element and an optional primary battery
- Automatically select the output between the internal supply, the load and the storage element

#### Load supply voltage

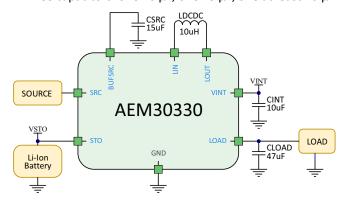
- Current drive capability: 30 mA in low power mode, 60 mA in high power mode
- Selectable load voltage from 1.2 V to 3.3 V

#### Battery protection features

- Selectable over-charge and over-discharge protection for any type of rechargeable battery or (super-)capacitor
- Fast super-capacitor charging
- Dual cell super-capacitor balancing circuit

#### Smallest footprint, smallest BOM

- Only four external components are required
- One 10 µH inductor
- Three capacitors: one 10  $\mu F$ , one 15  $\mu F$ , one at least 40  $\mu F$



## Description

The AEM30330 is an integrated energy management circuit that extracts DC power from an ambient energy harvesting source to simultaneously supply an application and store energy in a storage element. The AEM30330 allows to extend battery lifetime and ultimately eliminates the primary energy storage element in a large range of applications.

Thanks to its Maximum Power Point Tracking system, the AEM30330 extracts the maximum energy available from the source. It integrates an ultra-low power DCDC converter which operates with input voltages ranging from 100 mV to 4.5 V.

Two different storage elements can be connected: one for storing energy and another one for coupling the load output voltage. At start-up, user can choose to charge the storage element first or the load capacitor first.

With its unique cold start circuit, the AEM30330 can start harvesting with an input voltage as low as 275 mV and from an input power of 3  $\mu$ W. The preset protection levels determine the storage element voltages protection thresholds to avoid over-charging and over-discharging the storage element and thus avoiding damaging it. Those are set through configuration pins. Moreover, special modes can be obtained at the expense of a few configuration resistors.

The load voltage can be selected to cover most application needs, with a maximum available load current of 60 mA.

The chip integrates all active elements for powering a typical wireless sensor. Only three capacitors and one inductor are required.

## **Applications**

- Asset Tracking/Monitoring
- Industrial applications
- Retail ESL/ Smart sensors
- Aftermarket automotive
- Smart home/building

#### **Device Information**

Part Number	Package	Body size [mm]
10AEM30330J0000	QFN 40-pin	5x5mm

### **Evaluation Board**

Part Numb	er		
2AAEM30	330J0010		



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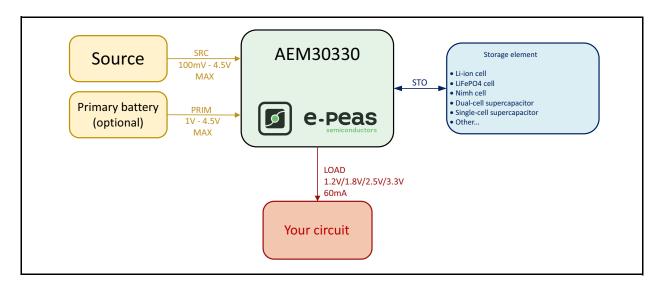


Figure 1: Simplified Schematic View

#### 1. Introduction

The AEM30330 is a full-featured energy efficient power management circuit able to harvest energy from an energy source (connected to SRC) to supply an application circuit (connected to LOAD) and use any excess of energy to charge a storage element (connected to STO). This is done with a minimal bill of material: only 3 capacitors and one inductor are needed for a basic setup.

The heart of the AEM30330 is a regulated switching DCDC converter with high power conversion efficiency.

At first start-up, as soon as a required cold start voltage of 275 mV and a sparse amount of power of at least 3  $\mu$ W is available at the source, the AEM30330 cold starts. After the cold start, the AEM extracts the power available from the source if the working input voltage is at least 100 mV.

Through four configuration pins (STO\_CFG[3:0]), the user can select a specific operating mode out of 15 modes that cover most application requirements without any dedicated external component. Those operating modes define the protection levels of the storage element. If none of those 15 modes fit the user's storage element, a custom mode is also available to allow the user to define a mode with custom specifications.

Status pins ST\_STO, ST\_STO\_RDY and ST\_STO\_OVDIS provide information about the voltage levels of the storage element. ST\_STO is asserted when the voltage of the storage element  $V_{STO}$  is above  $V_{CHRDY}$  and is reset when the voltage drops below  $V_{OVDIS}$ . ST\_STO\_RDY is asserted when  $V_{STO}$  is above  $V_{CHRDY}$ , and reset when  $V_{STO}$  drops below  $V_{CHRDY}$ . ST\_STO\_OVDIS is asserted when  $V_{STO}$  drops below  $V_{OVDIS}$  or

when the AEM30330 enters on PRIMARY BATTERY STATE, and reset when  $V_{STO}$  is above  $V_{OVDIS}$ . Status pin ST\_LOAD is asserted when the load voltage  $V_{LOAD}$  rises above  $V_{LOAD,TYP}$ , and is reset when  $V_{LOAD}$  drops below  $V_{LOAD,MIN}$ .

The Maximum Power Point (MPP) ratio is configurable thanks to three configuration pins (R\_MPP[2:0]) and ensures an optimum biasing of the harvester to maximize power extraction. Depending on the harvester, it is possible to adapt the timings of the MPP evaluations with the two configuration pins (T\_MPP[1:0]) that sets the periodicity and the duration of the MPP evaluation.

Once started, if at any time the load requires more power than can be harvested from the energy source, the AEM30330 automatically uses the storage element to keep the load supplied.

The AEM30330's DCDC converter can work in two modes: LOW POWER MODE and HIGH POWER MODE, each one of these being optimized for a power range on SRC and LOAD.

The charging of the storage element can be prevented by pulling EN\_STO\_CH to GND, typically to protect the storage element if the temperature is too low/high to safely charge it.

The AEM30330 also implements a SLEEP STATE, which reduces the quiescent current to avoid wasting the energy stored on the storage element when EN\_SLEEP is asserted.

At start-up, user can choose to prioritize starting the application circuit connected on LOAD, or charging the storage element connected on STO. This is set by the STO\_PRIO pin.



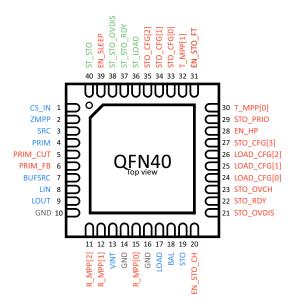


Figure 2: Pinout Diagram QFN 40-pin

NANAE	PIN NUMBER	FUNCTION	
NAME	QFN40		
Power pins			
CS_IN	1	Input for the cold start circuit.	
ZMPP	2	Used for the configuration of the ZMPP (optional). Must be left floating if not used.	
SRC	3	Connection to the harvested energy source.	
PRIM	4	Input for primary battery. Must be connected to GND if not used.	
BUFSRC	7	Connection to an external capacitor buffering the DCDC converter input.	
LIN	8	DCDC inductance connection.	
LOUT	9	DCDC inductance connection.	
VINT	13	Internal voltage supply.	
LOAD	17	Output voltage to supply on application load.	
BAL	18	Connection to mid-point of a dual-cell supercapacitor (optional). Must be connected to GND if not used.	
STO	19	Connection to the energy storage element - battery or (super-)capacitor. Cannot be left floating. Must be connected to a minimum capacitance of 100 $\mu F$ or to a rechargeable battery.	
Status pins			
ST_LOAD	36	Logic output. Asserted when the LOAD voltage $V_{LOAD}$ rises above the $V_{LOAD,TYP}$ threshold. Reset when $V_{LOAD}$ drops below $V_{LOAD,MIN}$ threshold. High level is $V_{LOAD}$ .	
ST_STO_RDY	37	Logic output. Asserted when $V_{STO}$ is above $V_{CHRDY}$ , reset when $V_{STO}$ drops below $V_{CHRDY}$ . High level is $V_{LOAD}$ .	
ST_STO_OVDIS	38	Logic output. Asserted when the AEM30330 state is SHUTDOWN STATE or PRIMARY BATTERY STATE, reset when in any other state. High level is V <sub>LOAD</sub> .	
ST_STO	40	Logic output. Asserted when the storage device voltage $V_{STO}$ rises above the $V_{CHRDY}$ threshold, reset when $V_{STO}$ drops below the $V_{OVDIS}$ threshold. High level is $V_{STO}$ .	

Table 1: Power and Status Pins



NAME	PIN NUMBER	Function		
NAME	QFN40			
Configuration pins				
R_MPP[0]	15			
R_MPP[1]	12	Used for the configuration of the MPP ratio.		
R_MPP[2]	11			
T_MPP[0]	30	Head for the configuration of the MDD timings		
T_MPP[1]	32	Used for the configuration of the MPP timings.		
LOAD_CFG[0]	24			
LOAD_CFG[1]	25	Used for the configuration of LOAD output voltage V <sub>LOAD</sub> .		
LOAD_CFG[2]	26			
STO_CFG[0]	33			
STO_CFG[1]	34	Used for the configuration of the threshold voltages for the		
STO_CFG[2]	35	energy storage element (V <sub>OVDIS</sub> , V <sub>CHRDY</sub> and V <sub>OVCH</sub> ).		
STO_CFG[3]	27			
STO DDIO	20	- Pulled up to VINT: storage device (STO) has highest priority at start-up.		
STO_PRIO	29	- Pulled down to GND: load (LOAD) has highest priority at start-up.		
STO_OVCH	23	Used for the configuration of the threshold voltages (V <sub>OVDIS</sub> , V <sub>CHRDY</sub> and V <sub>OVCH</sub> ) for the		
STO_OVDIS	21	energy storage element when STO_CFG[3:0] are set to custom mode (optional). Must		
STO_RDY	22	be left floating if not used.		
		- Pulled up to LOAD: SLEEP STATE enabled.		
EN_SLEEP 39		- Pulled down to GND: SLEEP STATE disabled.		
EN_STO_FT	31	<ul> <li>Pulled up to VINT: allows charges flowing directly from SRC to STO when SRC is above 5V.</li> </ul>		
EN_510_11	31	- Pulled down to GND: normal operation.		
		- Pulled up to LOAD: enables the charging of the storage element.		
EN_STO_CH	20			
		- Pulled down to GND: disables the charging of the storage element.		
EN_HP	28	- Pulled up to VINT: HIGH POWER MODE enabled.		
		- Pulled down to GND: HIGH POWER MODE disabled.		
PRIM_CUT	5	Used for the configuration of the primary battery. Must be left floating if not used.		
PRIM_FB	6	Used for the configuration of the primary battery. Must be connected to GND if not used.		
Other				
GND	10, 14, 16	Ground connection, best possible connection to PCB ground plane.		
3/10	Exposed pad	Ground connection, best possible connection to FCB ground plane.		

Table 2: Configuration and Ground Pins



# 2. Absolute Maximum Ratings

Parameter	Value
Voltage on LOAD, STO, SRC, BUFSRC, LIN, LOUT, ZMPP, BAL, CS_IN, PRIM, EN_SLEEP, EN_STO_CH	-0.3 V to 5.5 V
Voltage on VINT, T_MPP[1:0], R_MPP[2:0], LOAD_CFG[2:0], STO_CFG[3:0], STO_PRIO, STO_OVCH, STO_OVDIS, STO_RDY, EN_HP, PRIM_CUT, PRIM_FB	-0.3 V to 2.75 V
Operating junction temperature	-40 °C to 125 °C
Storage temperature	-65 °C to 150 °C
ESD HBM voltage	> 2000 V
ESD CDM voltage	> 500 V

Table 3: Absolute Maximum Ratings

## 3. Thermal Resistance

Package	θЈА	θЈС	Unit
QFN 40- pin	TBD	TBD	°C/W

Table 4: Thermal Resistance

#### **ESD CAUTION**



ESD (ELECTROSTATIC DISCHARGE) SENSITIVE DEVICE

These devices have limited built-in ESD protection and damage may thus occur on devices subjected to high-energy ESD. Therefore, proper EESD precautions should be taken to avoid performance degradation or loss of functionality

Table 5: ESD Caution



# 4. Typical Electrical Characteristics at 25 °C

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
Power Conversion	on					
P <sub>SRC,CS</sub>	Source power required for cold	V <sub>STO</sub> > Vchrdy		3		μW
' SRC,CS	start	V <sub>STO</sub> < Vchrdy		6		μW
V <sub>SRC</sub>	Input voltage of the energy	During cold start		0.275	4.5	V
SRC	source	After cold start	0.1		4.5	V
R <sub>ZMPP</sub>	MPPT ratio	see Table 11		65, 70, 75 or 8 MPP[2:0] config		%
Timing						
T <sub>MPP,EVAL</sub>	Duration of a MPP evaluation		50% of Table 8		200% of Table 8	ms
T <sub>MPP,PERIOD</sub>	Time between two MPP evaluation	S	50% of Table 8		200% of Table 8	S
Storage element	t					
V <sub>OVCH</sub>	Maximum voltage accepted on the storage element before disabling its charging					V
$V_{CHRDY}$	Minimum voltage required on the storage element before asserting the ST_STO	see Table 9	Depends on STO_CFG[3:0] configuration		V	
V <sub>OVDIS</sub>	Minimum voltage accepted on the storage element before entering into SHUTDOWN STATE				V	
Load Output Vo	ltage					
		V <sub>LOAD</sub> = 1.8V V <sub>STO</sub> > 1.6V HP_EN = 1		60		
I <sub>LOAD,MAX</sub>	LOAD current drive capability	V <sub>LOAD</sub> = 2.5V V <sub>STO</sub> > 1.6V HP_EN = 1		60		mA
		V <sub>LOAD</sub> = 3.3V V <sub>STO</sub> > 1.8V HP_EN = 1		60		-
$V_{LOAD}$	Output voltage	see Table 10	Depends on configuration	LOAD_CFG[2:0]		V
Internal supply 8	& Quiescent Current					
V <sub>VINT</sub>	Internal voltage supply			2.2		V
l <sub>Q</sub>	Quiescent current on STO	V <sub>STO</sub> = 3.7V V <sub>LOAD</sub> = 2.5V EN_SLEEP = 0 HP_EN = 0		875		nA
Symbol	Logic Level		Low H		igh	
Logic output pin	is .					
ST_STO	Logic output levels on the status ST	O pins	G	ND	V	STO
 ST_LOAD	Logic output levels on the status LOAD pins				OAD	
31_60/10						
ST_STO_RDY	Logic output levels on the status ST		GI	ND		OAD

Table 6: Typical Electrical Characteristics



# **5. Recommended Operation Conditions**

Symbol	Parameter	Min	Тур	Max	Unit	
External Component	S					
LDCDC	Inductor of the DCDC converter	10 μΗ		μН		
CSRC	Capacitor decoupling the SRC terminal	15			μF	
CINT	Capacitor decoupling the VINT terminal	10			μF	
CLOAD	Capacitor decoupling the LOAD terminal	40			μF	
CSTO	Optional - Capacitor on STO if no storage element is connected (see Section 8.10.1)	100			μF	
STO_OVCH	Configuration of V <sub>OVCH</sub> in custom mode					
STO_OVDIS	Configuration of V <sub>OVDIS</sub> in custom mode	1	Section 8.4	100	МΩ	
STO_RDY	Configuration of V <sub>CHRDY</sub> in custom mode		8.4			
PRIM_FB	Configuration of V	100 Section		500	kΩ	
PRIM_CUT	Configuration of V <sub>PRIM,MIN</sub>	100	8.9	300	K22	
ZMPP	Optional - Used for the configuration of the ZMPP tracking function	10	Section 8.7	100K	Ω	
Symbol	Logic Level	Low		High		
Logic input pins						
R_MPP[2:0] Configuration pins for the MPP evaluation GND		VINT				
T_MPP[1:0]	Configuration pins for the MPP timing	GND VINT		NT		
LOAD_CFG[2:0]	Configuration pins for the LOAD voltage	GND		V	NT	
STO_CFG[3:0]	Configuration pins for the STO voltage	GND		V	NT	
STO_PRIO	Configuration pin for the controller	GND		V	VINT	
EN_STO_FT	Configuration pin for the controller	GND VIN		NT		
EN_SLEEP	Configuration pin for the controller	GND LOAD		)AD		
EN_STO_CH	Configuration pin for the controller	GND LOAD		)AD		
EN_HP	Configuration pin for the controller	GND VINT		NT		

Table 7: Recommended Operation Conditions



# 6. Functional Block Diagram

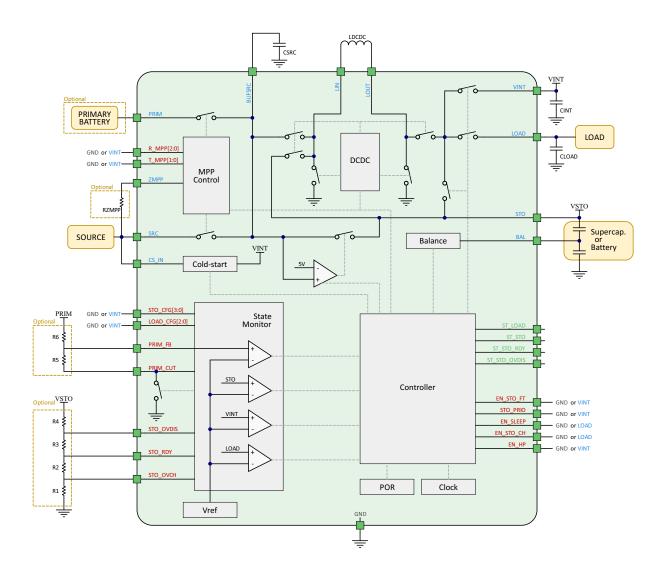


Figure 3: Functional Block Diagram



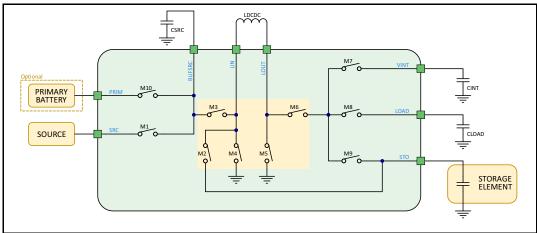


Figure 4: Simplified Schematic View of the AEM30330

## 7. Theory of Operation

#### 7.1. DCDC Converter

The DCDC converter converts the voltage available at BUFSRC or at STO to a level suitable for charging the storage element STO or to regulate the LOAD and the internal supply VINT. The switching transistors of the DCDC converter are M2 or M3, M4, M5 and M6. Thanks to M7, M8 and M9, the controller selects between LOAD, STO and VINT respectively as the converter output. M1 and M10 selects respectively the source or the primary battery as main input of energy. The internal supply VINT is regulated with priority over LOAD. STO is selected as an output only when neither VINT nor LOAD needs to be supplied. The converter has two possible inputs: BUFSRC or STO. BUFSRC is used by default as an input via M3. If the energy available on SRC is not sufficient to maintain the LOAD or VINT voltage, for instance because of a sudden current peak on LOAD, the converter uses STO instead as an input via M2 to keep LOAD and VINT regulated.

The reactive power component of this converter is the external inductor LDCDC. Periodically, the MPP control circuit

disconnects the source from the BUFSRC pin with the transistor M1 in order to let the harvester on SRC rise to its open-circuit voltage  $V_{OC}$  and measure it. This is done to define the optimal voltage level  $V_{MPP}$ , which is determined by applying the MPP ratio on  $V_{OC}$ . BUFSRC is decoupled by the capacitor CSRC, which smooths the voltage against the current pulses pulled by the DCDC converter. The storage element is connected to the STO pin.

Depending on its input voltage and its output voltage, the DCDC converter will work as a boost converter, a buck converter or a buck-boost converter. The maximum power that can be harvested and supplied to the output LOAD depends on the power mode (HIGH POWER MODE or LOW POWER MODE), which is configured through the EN\_HP pin (see Section 8.1).

DCDC converter mode	Input Voltage / Output Voltage
Boost	<b>V<sub>IN</sub> &lt; V<sub>OUT</sub> -</b> 250mV
Buck	<b>V<sub>IN</sub> &gt; V<sub>OUT</sub> +</b> 250 mV
Buck - Boost	<b>V<sub>OUT</sub></b> - 250mV < <b>V<sub>IN</sub></b> < <b>V<sub>OUT</sub></b> + 250mV

**Table 8: DCDC Converter Modes** 



### 7.2. Reset, Wake Up and Start States

The RESET STATE is a state where all nodes are deeply discharged and there is no available energy to be harvested. As soon as the required cold start voltage of 275 mV and a sparse amount of power of just 3 µW become available on CS\_IN (usually connected to SRC), the AEM30330 switches to WAKE-UP STATE, and energy is extracted from SRC to make V<sub>VINT</sub> rise to 2.2 V. When V<sub>VINT</sub> reaches those 2.2 V, the AEM30330 switches to START STATE. In START STATE, two scenarios are possible: in the first scenario, STO\_PRIO is asserted, the storage element connected to STO has the priority on the one connected to LOAD. In the second scenario, STO\_PRIO is reset and the LOAD has the priority.

When the AEM30330 is in RESET STATE, WAKE-UP STATE or START STATE, the DCDC converter's input is always BUFSRC: STO is never used as input. This guarantees that the storage element is not used until a minimum amount of energy has been stored in it.

#### 7.2.1. Storage Element Priority

This paragraph covers the AEM30330 behaviour when STO\_PRIO is pulled up to VINT, so that the storage element connected on STO has priority over LOAD.

#### **Supercapacitor as a Storage Element**

If the storage element is a supercapacitor, it may be fully discharged at first and thus need to be charged from 0 V. The DCDC converter charges STO from the input source (SRC). When  $V_{STO}$  reaches  $V_{CHRDY}$ , the circuit enters SUPPLY STATE.

#### **Battery as a Storage Element**

If the storage element is a battery, but its voltage is lower than  $V_{CHRDY}$ , then the storage element needs to be charged first until it reaches  $V_{CHRDY}$ . Once  $V_{STO}$  reaches  $V_{CHRDY}$ , or if the battery was initially charged above  $V_{CHRDY}$ , the circuit enters SUPPLY STATE.

#### 7.2.2. Load Priority

If STO\_PRIO is connected to GND, the AEM charges first the LOAD to V<sub>LOAD,MAX</sub> (see Table 10) using energy from the source (SRC). This allows to first supply the application circuit connected to LOAD. If the storage element was initially charged above V<sub>CHRDY</sub>, the circuit enters SUPPLY STATE as soon as LOAD reaches V<sub>LOAD,TYP</sub>. If the storage element is a supercapacitor or a battery which voltage is lower than V<sub>CHRDY</sub>, the AEM keeps regulating LOAD between V<sub>LOAD,MAX</sub> and V<sub>LOAD,TYP</sub>. Meanwhile, any excess charges on the source is used to charge the storage element until it reaches V<sub>CHRDY</sub>. Once V<sub>STO</sub> exceeds V<sub>CHRDY</sub>, the circuit enters into SUPPLY STATE.

This configuration is useful when a large storage element is connected to STO and a smaller one is connected to LOAD: the application starts as soon as CLOAD is charged and does not have to wait for the large storage element on STO to be charged.



### 7.3. Supply State

In SUPPLY STATE, four scenarios are possible:

- There is enough power provided by the source (SRC) to keep V<sub>LOAD</sub> near V<sub>LOAD,TYP</sub> with a small hysteresis and V<sub>VINT</sub> at 2.2 V. The excessive power is used to charge the storage element on STO. In that case, the circuit remains in SUPPLY STATE. If STO is fully charged, LOAD will be maintained at V<sub>LOAD,MAX</sub> instead of V<sub>LOAD,TYP</sub>.
- If the circuit connected to LOAD consumes more energy than the energy that the AEM30330 is able to extract from the source, the LOAD circuit will be

- supplied by the storage element connected to the STO terminal. In this case, the circuit stays in SUPPLY STATE.
- Due to a lack of power from the source, V<sub>STO</sub> falls below V<sub>OVDIS</sub>. In this case, the circuit enters SHUTDOWN STATE as explained in Section 7.4.
- If EN\_SLEEP is asserted and conditions (shown on Figure 5) on V<sub>LOAD</sub> and V<sub>VINT</sub> are satisfied, the AEM enters SLEEP STATE (see section 7.5).

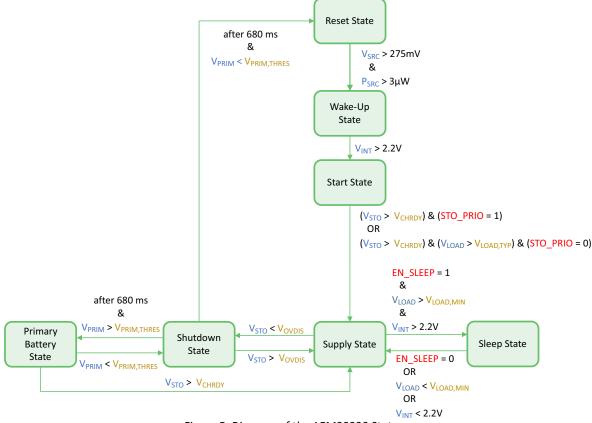


Figure 5: Diagram of the AEM30330 States

#### 7.4. Shutdown State

If the storage element gets depleted ( $V_{STO} < V_{OVDIS}$ ), the AEM30330 goes to SHUTDOWN STATE. As long as the AEM30330 is in this state, the ST\_STO\_OVDIS is asserted. In SHUTDOWN STATE, if  $V_{STO}$  recovers within 680 ms, the AEM30330 goes back to SUPPLY STATE. This prevents false detection of the storage element being empty because of a LOAD current peak. However, if  $V_{STO}$  remains lower than

V<sub>OVDIS</sub> for at least 680 ms, the circuit enters then PRIMARY BATTERY STATE if a suitable primary battery has been detected on PRIM, else it enters RESET STATE.



### 7.5. Sleep State

SLEEP STATE reduces the AEM30330 quiescent current by disabling the DCDC converter and by reducing the controller clock frequency. If VINT voltage or V<sub>LOAD</sub> fall below their regulation value, the AEM30330 temporarily exits SLEEP STATE to wake up the DCDC converter and supply VINT or LOAD. Exiting SLEEP STATE and waking up the DCDC converter takes up to 1 ms. Depending on the expected LOAD current, CLOAD value must be adapted to act as an energy buffer during the 1 ms required to wake up the DCDC converter. Therefore, this mode should be used when LOAD current is small. As the DCDC is enabled, no energy is harvested from SRC while in SLEEP STATE.

The AEM30330 enters SLEEP STATE if **all** the following conditions are satisfied:

- EN\_SLEEP pin pulled up to LOAD
- V<sub>VINT</sub> > 2.2 V
- V<sub>LOAD</sub> > V<sub>LOAD,TYP</sub>

The AEM30330 leaves SLEEP STATE and switches back to SUPPLY STATE if **one** of the following conditions is satisfied:

- EN\_SLEEP pin pulled down to GND
- V<sub>VINT</sub> < 2.2 V
- V<sub>LOAD</sub> < V<sub>LOAD,TYP</sub>

The AEM30330 will then stay in SUPPLY STATE until the SLEEP STATE conditions are all satisfied again.

#### 7.6. Primary Battery State

When V<sub>STO</sub> drops below V<sub>OVDIS</sub>, the circuit compares the voltage on PRIM\_FB to a 1V voltage reference to determine whether a charged primary battery is connected on PRIM. The voltage on PRIM\_FB is set thanks to two optional resistances as explained in Section 8.9. If the voltage on PRIM\_FB is higher than 1V, the circuit considers the primary battery as available and the circuit enters PRIMARY BATTERY STATE as shown on Figure 5.

In that mode, transistor M1 is opened and the primary battery is connected to BUFSRC through transistor M10 to become the energy source for the AEM30330. The chip remains in PRIMARY BATTERY STATE until  $V_{STO}$  reaches  $V_{CHRDY}$ , where the circuit switches to SUPPLY STATE. As long as the AEM30330 is in PRIMARY BATTERY STATE, ST\_STO\_OVDIS is asserted.

### 7.7. Maximum Power Point Tracking

During SUPPLY STATE, SHUTDOWN STATE and START STATE, the voltage on SRC is regulated by an internal Maximum Power Point Tracking (MPPT) module. The MPPT module evaluates  $V_{MPP}$ , the voltage at which the source provides the highest possible power, as a given fraction of the open-circuit voltage of the source  $V_{OC}$ . This ratio is set by the R\_MPP[2:0] terminals according to Table 7. The sampling period and duration are set according to Table 8 by the T\_MPP[1:0] terminals. The AEM30330 supports any  $V_{MPP}$  levels in the range from 100 mV to 4.5 V. It offers a choice of seven values for the  $V_{MPP}$  /  $V_{OC}$  fraction. It can also match the input impedance of the DCDC converter with an impedance connected to the ZMPP terminal as explain as explained in section 8.7.

### 7.8. Balancing for Dual-Cell Supercapacitor

The balancing circuit allows the user to balance the internal voltage of the dual-cell supercapacitor connected to STO in order to avoid damaging the supercapacitor because of excessive voltage on one cell.

If BAL is connected to GND, the balancing circuit is disabled. This configuration must be used if a battery, a capacitor or a single-cell supercapacitor is connected on STO.

If BAL is connected to the node between both cells of a supercapacitor, the balancing circuit compensates for any mismatch of the two cells that could lead to the over-charge of one of two cells. The balancing circuit ensures that BAL remains close to V<sub>STO</sub> / 2. This configuration must be used if a dual-cell supercapacitor is connected to STO, and that this supercapacitor requires cells balancing.

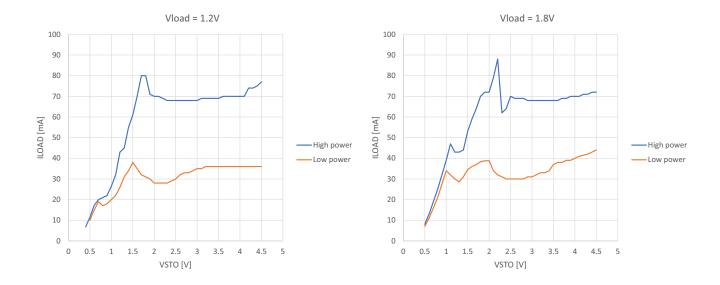


## 8. System Configuration

## 8.1. High Power / Low Power Mode

When EN\_HP is pulled to VINT, the DCDC converter is configured to HIGH POWER MODE. This allows higher currents to be extracted from the DCDC converter input (SRC, STO or PRIM) to the DCDC converter output (LOAD or STO).

Figure 6 shows the maximum current that the DCDC converter can supply to LOAD, depending on the storage voltage  $V_{STO}$ , for every available load voltage  $V_{LOAD}$ , for both HIGH POWER MODE and LOW POWER MODE.



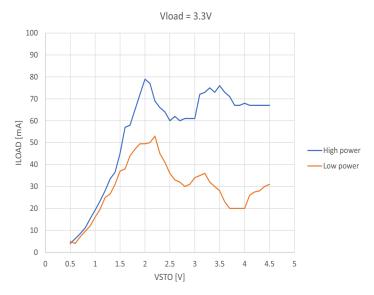


Figure 6: Maximum LOAD Current Depending on  $V_{STO}$  and on  $V_{LOAD}$ 



### 8.2. Storage Element Configuration

Through four configuration pins (STO\_CFG[3:0]), the user can set a particular operating mode from a range that covers most application requirements, without any dedicated external component as shown in Table 9. The three threshold levels are defined as:

- V<sub>OVCH</sub>: maximum voltage accepted on the storage element before disabling its charging.
- V<sub>CHRDY</sub>: minimum voltage required on the storage element before starting to supply the LOAD (if STO\_PRIO is asserted) and entering supply state after start-up.

 V<sub>OVDIS</sub>: minimum voltage accepted on the storage element before considering the storage element as depleted resetting ST\_STO.

A large-size storage element is not mandatory on STO:

- If the harvested energy source is permanently available and covers the application needs or
- If the application does not need to store energy when the harvested energy source is not available

The storage element may then be replaced by an external capacitor CSTO with a minimum value of 100  $\mu F$ .

Caution: running the AEM30330 without this 100  $\mu\text{F}$  minimum capacitance on STO will permanently damage the circuit.

Configuration pins				Storage element threshold voltages			Typical use
STO_CFG[3]	STO_CFG[2]	STO_CFG[1]	STO_CFG[0]	V <sub>OVDIS</sub>	V <sub>CHRDY</sub>	V <sub>OVCH</sub>	
0	0	0	0	3.00 V	3.50 V	4.05 V	Li-ion battery
0	0	0	1	2.80 V	3.10 V	3.60 V	LiFePO4 battery
0	0	1	0	1.85 V	2.40 V	2.70 V	NiMH battery
0	0	1	1	0.20 V	1.00 V	4.65 V	Dual-cell supercapacitor
0	1	0	0	0.20V	1.00 V	2.60 V	Single-cell supercapacitor
0	1	0	1	1.00 V	1.20 V	2.95 V	Single-cell supercapacitor
0	1	1	0	1.85 V	2.30 V	2.60 V	NGK
0	1	1	1	Custom Mode			ode
1	0	0	0	1.10 V	1.25 V	1.50 V	Ni-Cd 1 cells
1	0	0	1	2.20 V	2.50 V	3.00 V	Ni-Cd 2 cells
1	0	1	0	1.45 V	2.00 V	4.65 V	Dual-cell supercapacitor
1	0	1	1	1.00 V	1.20 V	2.60 V	Single-cell supercapacitor
1	1	0	0	2.00 V	2.30 V	2.60 V	ITEN / Umal Murata
1	1	0	1	3.00 V	3.50 V	4.35 V	Li-Po battery
1	1	1	0	2.60 V	2.70 V	4.00 V	Tadiran TLI1020A
1	1	1	1	2.60 V	3.50 V	3.90 V	Tadiran HLC1020

Table 9: Storage Element Configuration Pins



## 8.3. Load Configuration

The LOAD output voltage V<sub>LOAD</sub> can be configured thanks to the LOAD\_CFG[2:0] configuration pins covering most application cases (see Table 10). VLOAD is regulated to

V<sub>LOAD,TYP</sub>. However, if V<sub>LOAD</sub> falls below V<sub>LOAD,MID</sub>, the controller forces STO as an input of the DCDC converter to supply LOAD.

Configuration p	ins	IOAD output voltage				
LOAD_CFG[2]	LOAD_CFG[1]	LOAD_CFG[0]	V <sub>LOAD,MIN</sub>	V <sub>LOAD,MID</sub>	V <sub>LOAD,TYP</sub>	V <sub>LOAD,MAX</sub>
0	0	0	3.15 V	3.23 V	3.28 V	3.34 V
0	0	1	2.35 V	2.47 V	2.50 V	2.53 V
0	1	0	1.64 V	1.75 V	1.79 V	1.82 V
0	1	1	1.14 V	1.16 V	1.20 V	1.23 V
1	0	0	1.39 V	1.56 V	1.61 V	2.63 V
1	0	1	1.39 V	1.56 V	1.61 V	4.65 V
1	1	0	Reserved, do not use			
1	1	1				

Table 10: Load Configuration Pins

## 8.4. Custom Mode Configuration

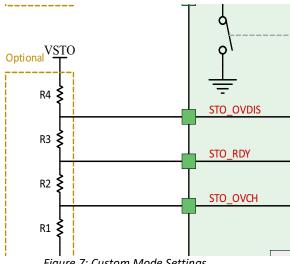


Figure 7: Custom Mode Settings

When STO\_CFG[3:0] = 0111, the custom mode is selected and all four configuration resistors must be wired as shown in Figure 7.

V<sub>OVCH</sub>, V<sub>CHRDY</sub> and, V<sub>OVDIS</sub> are defined thanks to R1, R2, R3 and R4, which can be determined within the following constraints:

- -RT = R1 + R2 + R3 + R4
- $1 M\Omega \le RT \le 100 M\Omega$
- R1 = RT (1 V /  $V_{OVCH}$ )
- R2 = RT (1 V / V<sub>CHRDY</sub> 1 V / V<sub>OVCH</sub>)
- R3 = RT (1 V / V<sub>OVDIS</sub> 1 V / V<sub>CHRDY</sub>)

- R4 = RT (1 - 1 V / V<sub>OVDIS</sub>)

The resistors should have high values to make the additional power consumption negligible. Moreover, the following constraints must be adhered to ensure the functionality of the chip:

- $V_{CHRDY}$  + 0.05 V ≤  $V_{OVCH}$  ≤ 4.5 V
- $V_{OVDIS}$  + 0.05 V ≤  $V_{CHRDY}$  ≤  $V_{OVCH}$  0.05 V
- 1V ≤ V<sub>OVDIS</sub>

### 8.5. Disable Storage Element Charging

Pulling down EN STO CH pin to GND disables the charging of the storage element connected to STO, either from SRC or from PRIM. This can be done for example to protect the storage element when the system detects that the environment temperature is too low or too high to safely charge the storage element.

While EN STO CH is pulled down, VINT and LOAD can still be supplied either from SRC, from STO or from PRIM.

To enable charging the storage element on STO, EN\_STO\_CH must be pulled up to LOAD.

NOTE: STO will still be charged to V<sub>CHRDY</sub> during the START



### 8.6. MPPT Configuration

There are two kinds of pins to configure the maximum point tracking. The first configuration pins allows for selecting the MPP tracking ratio based on the characteristic of the input power source. The configuration pins are R\_MPP[2:0].

	Configuration	on pins	MPPT ratio
R_MPP[2]	R_MPP[1]	R_MPP[0]	V <sub>MPP</sub> / V <sub>OC</sub>
0	0	0	35%
0	0	1	50%
0	1	0	60%
0	1	1	65%
1	0	0	70%
1	0	1	75%
1	1	0	80%
1	1	1	ZMPP

Table 11: MPP Ratio Configuration Pins

The second kind of configuration pins allows for configuring the duration of an MPP evaluation and the time between two MPP evaluations. The configurations pins are T\_MPP[1:0]

Configuration	pins	MPPT timing		
T_MPP[1]	T_MPP[0]	Sampling duration	Sampling period	
0	0	3.82 ms	18.28 ms	
0	1	5.1 ms	280.0 ms	
1	0	71.6 ms	1.12 s	
1	1	1.12 s	71.7 s	

Table 12: MPP Timing Configuration Pins

## 8.7. ZMPP Configuration

Instead of working at a ratio of the open-circuit voltage, the AEM30330 can regulate the input impedance of the DCDC converter so that it matches a constant impedance  $R_{\sf ZMPP}$  connected to the  $\sf ZMPP$  pin. In this case, the AEM30330 regulates  $V_{\sf SRC}$  at a voltage that is the product of the  $\sf ZMPP$  resistance  $R_{\sf ZMPP}$  and the current available at the SRC input.

- 10 Ω ≤  $R_{ZMPP}$  ≤ 100 KΩ

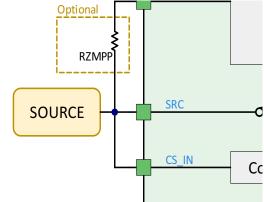


Figure 8: R<sub>ZMPP</sub> Connection to the AEM30330

## 8.8. Source to Storage Element Feed-Through

When the harvester connected to SRC delivers a high amount of power, the AEM might not be able to pull enough current to regulate  $V_{SRC}$  to the MPP voltage. The voltage on SRC thus increases, eventually above 5V. To maximize the energy extracted in that case, the AEM30330 can be configured to create a direct feed-through current path from SRC to STO when  $V_{SRC}$  is above 5V. This is measured when the AEM is pulling current from the source (not during an MPP evaluation).

If the MPPT module detects that  $V_{SRC}$  is higher than 4 V and EN\_STO\_FT is set, the SRC is monitored. From that moment, if the AEM30330 detects that  $V_{SRC}$  rises above 5 V and if the storage element is not fully charged, the switch between the SRC and STO pins is closed until  $V_{SRC}$  drops below 5 V or until the storage element is fully charged.

This feature is enabled by pulling up EN\_STO\_FT pin to VINT. However, it is disabled if the storage element is fully charged, or when a MPP evaluation is occurring. Therefore the circuit must still be protected from any overshoot voltage on SRC above 5.5 V, for instance by a zener diode.



## 8.9. Primary Battery Configuration

To use the primary battery, it is mandatory to determine V<sub>PRIM,MIN</sub>, the voltage of the primary battery at which it has to be considered as empty. This is to prevent over-discharging the primary battery, which could lead to hazardous behaviour of the primary battery.

The circuit uses a resistive divider between PRIM and PRIM\_CUT to define the voltage on PRIM\_FB. V<sub>PRIM,MIN</sub> is evaluated by comparing the voltage on PRIM\_FB to an internal 1V voltage reference.

During the evaluation of  $V_{PRIM,MIN}$ , the circuit connects  $PRIM\_CUT$  to GND, thus letting current flow in the resistive voltage divider. When  $V_{PRIM,MIN}$  is not evaluated,  $PRIM\_CUT$  is left floating to avoid quiescent current on the resistive divider.

We define the total resistance (R6 + R5) as RP. R6 and R5 are calculated as:

- $100 \text{ k} \le \text{RP} \le 500 \text{ k}$
- R5 = RP \* 1V / V<sub>PRIM.MIN</sub>

- R6 = RP - R5

NOTE: PRIM and PRIM\_FB must be tied to GND if no primary battery is used. PRIM CUT can then be left floating.

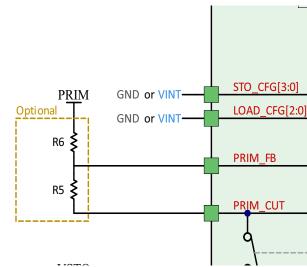


Figure 9: V<sub>PRIM,MIN</sub> Configuration Through a Resistive Divider



#### 8.10. External Components

Refer to Figure 3 to have an illustration of the external components wiring.

#### 8.10.1. Storage element information

The energy storage element of the AEM30330 can be a rechargeable battery, a supercapacitor or a capacitor. The size of the storage element must be determined so that its voltage does not fall below V<sub>OVDIS</sub> even during current peaks pulled by the application circuit connected to LOAD. If the internal resistance of the storage element cannot sustain this voltage limit, it is advisable to decouple the battery with a capacitor.

If the application expects a disconnection of the battery (e.g. because of a user removable connector), the PCB should include a capacitor CSTO of at least 100  $\mu\text{F}$  connected between STO and GND. The leakage current of the storage element should be small as leakage currents directly impact the quiescent current of the whole subsystem.

#### 8.10.2. External inductor information

The AEM30330 operates with one standard miniature

inductor. LDCDC must sustain a peak current of at least 1 A and a switching frequency of at least 10 MHz. Low equivalent series resistance (ESR) favours the power conversion efficiency of the DCDC converter. The recommended value is 10  $\mu\text{H}$ .

#### 8.10.3. External capacitors information

#### **CSRC**

This capacitor acts as an energy buffer at the input of the DCDC converter. It prevents large voltage fluctuations when the DCDC converter is switching. The recommended value is  $15\,\mu\text{F}$ .

#### **CINT**

This capacitor acts as an energy buffer for the internal voltage supply. The recommended value is 10  $\mu F$ .

#### CLOAD

This capacitor acts as an energy buffer for LOAD. It also reduces the voltage ripple induced by the current pulses inherent to the switched behaviour of the converter. The recommended value is at least 40  $\mu F$ .



## 9. Typical Application Circuits

### 9.1. Example Circuit 1

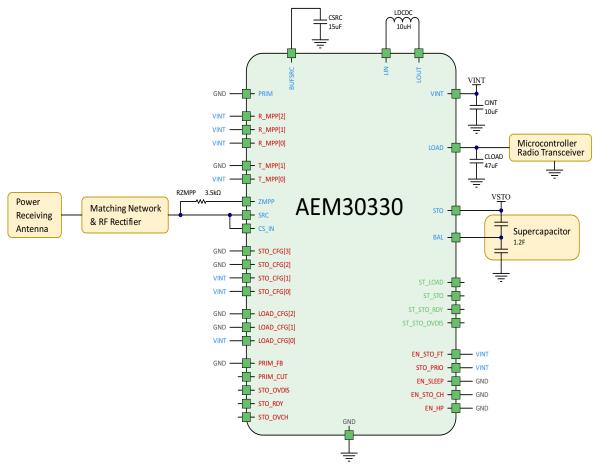


Figure 10: Typical Application Circuit 1

The circuit is an example of a system with Radio Frequency (RF) energy harvesting. It uses a pre-defined operating mode that use standard components, and a supercapacitor as energy storage.

- Energy source: RF source
- R\_MPP[2:0] = 111: the MPP tracker system is set to ZMPP, so that the AEM30330 will regulate SRC input resistance to  $R_{ZMPP}$  = 3.5 k $\Omega$  (see Section 8.7)
- T\_MPP[1:0] = 01: the MPP sampling period is 280 ms and the MPP sampling duration is 5.1 ms
- STO\_CFG[3:0] = 0011: the storage element is a dual-cell supercapacitor, with:
  - V<sub>OVCH</sub> = 4.65 V
  - V<sub>CHRDY</sub> = 1.00 V
  - V<sub>OVDIS</sub> = 0.20 V

- The balancing pin of the dual-cell supercapacitor is connected to BAL
- LOAD\_CFG[2:0] = 001: the micro-controller and the radio transceiver are supplied by the LOAD terminal, which is regulated at V<sub>LOAD</sub> = 2.5 V
- There is no primary battery connected to PRIM:
   PRIM FB and PRIM are connected to GND
- STO\_PRIO is connected to VINT: at start-up STO will be charged and before LOAD
- EN\_SLEEP is connected to GND: the AEM30330 will never switch to SLEEP STATE
- EN\_STO\_CH is connected to GND: the charging of the storage element on STO is disabled
- EN\_HP is connected to GND: the DCDC converter is in LOW POWER MODE



### 9.2. Example Circuit 2

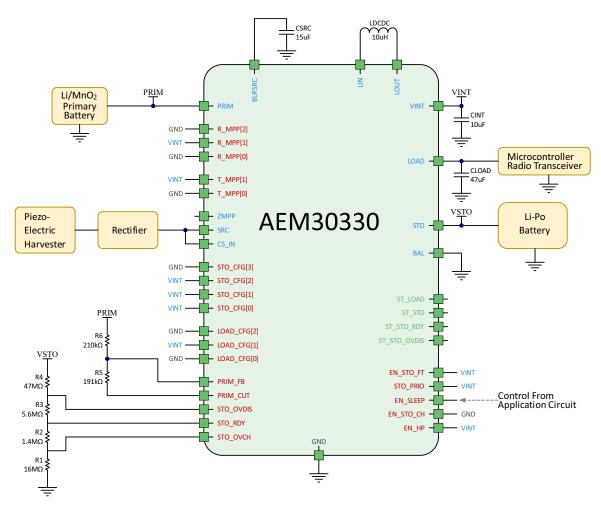


Figure 11: Typical Application Circuit 2

The circuit is an example of a system with vibration energy harvesting. It uses a Li-Po rechargeable battery as energy storage, which voltages thresholds are set by the custom mode.

Please note that the custom mode is used for the sake of the example, but most applications that use a Li-Po battery as storage element could use a pre-defined mode that does not require to implement the resistive divider (R1-R2-R3-R4), and thus have a reduced bill of material compared to the circuit shown on Figure 21.

- Energy source: piezoelectric vibration harvester
- R\_MPP[2:0] = 010: the MPP ratio is set to 60%
- T\_MPP[1:0] = 10: the MPP sampling period is 1.12 s and the MPP sampling duration is 71.6 ms.

- STO\_CFG[3:0] = 0111: the storage element is a Li-Po rechargeable battery, used with custom mode (in this example we set V<sub>CHRDY</sub> to 4.0V instead of the 3.51V on STO\_CFG[3:0] = 1101 preset):
  - V<sub>OVCH</sub> = 4.35V
  - V<sub>CHRDY</sub> = 4.00V
  - V<sub>OVDIS</sub> = 3.03V
- Custom mode resistor divider calculations (values have been rounded to the closest available value):
  - $RT = 70M\Omega$
  - R1 = 70MΩ \* (1V / 4.35V) ≈ 16MΩ
  - $R2 = 70M\Omega * (1V / 4.00V 1V / 4.35V) \approx 1.4M\Omega$
  - R3 =  $70M\Omega * (1V / 3.03V 1V / 4.00V) \approx 5.6M\Omega$
  - R4 = 70MΩ \* (1 1V / 3.03V) ≈ 47MΩ
- BAL is not used (not a dual-cell storage element) so it is connected to GND.



- LOAD\_CFG[2:0] = 010: the micro-controller and the radio transceiver are supplied by the LOAD terminal, which is regulated at V<sub>LOAD</sub> = 1.8V
- PRIM is a Li/MnO2 battery which has an overdischarge voltage of 2.1V. Thus we set R5 and R6 so that V<sub>PRIM,MIN</sub> = 2.1V:
  - $RP = 400k\Omega$
  - R5 = 1V \* 400kΩ / 2.1V ≈ 191kΩ
  - $R6 = 400k\Omega 191k\Omega \approx 210k\Omega$

- STO\_PRIO is connected to VINT: at start-up STO will be charged and before LOAD
- EN\_SLEEP is controlled by the application circuit, typically by a micro-controller GPIO output
- connected to LOAD: the charging of the storage element present on STO is enabled
- EN\_HP is connected to VINT: the DCDC converter is in HIGH POWER MODE



#### 9.3. Circuit Behaviour

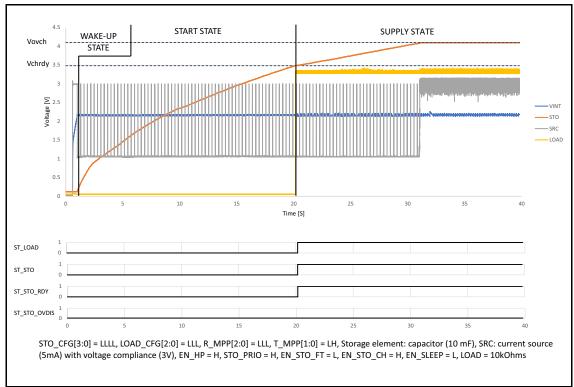


Figure 12: Wake-up state, Start state and Supply state

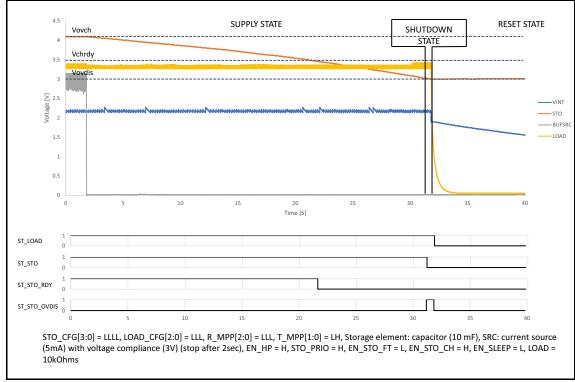


Figure 13: Supply state, Shutdown state and Reset state



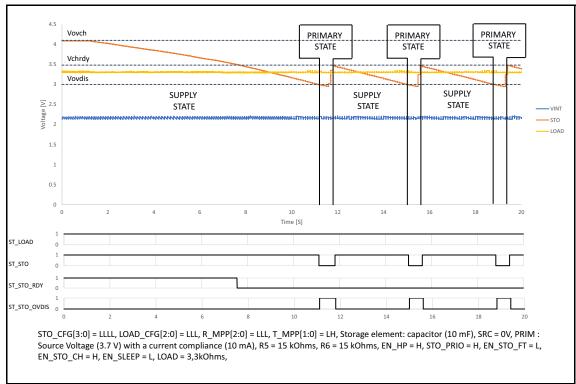


Figure 14: Primary State



## 10. Performance Data

## 10.1. DCDC Conversion Efficiency From SRC to STO in Low Power Mode

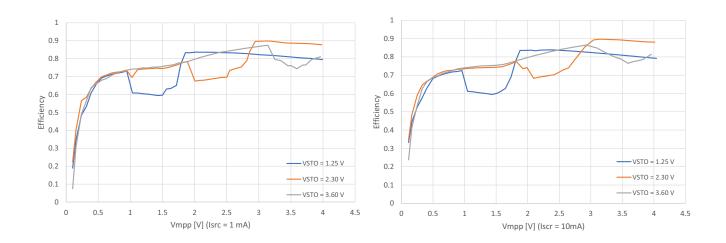


Figure 15: DCDC Efficiency from SRC to STO for 1 mA and 10 mA in Low Power Mode

## 10.2. DCDC Conversion Efficiency From SRC to STO in High Power Mode

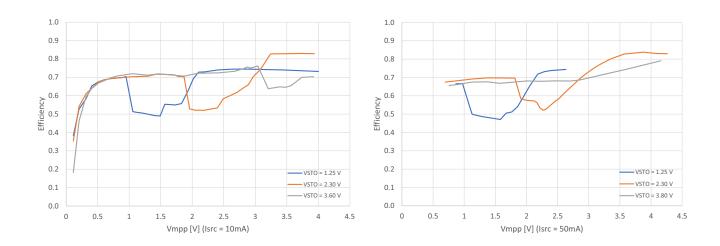


Figure 16: DCDC Efficiency from SRC to STO for 10 mA and 50 mA in High Power Mode



## 10.3. DCDC Conversion Efficiency From STO to LOAD in Low Power Mode

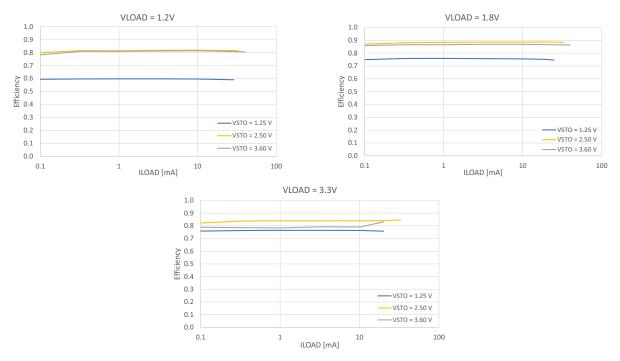


Figure 17: DCDC Efficiency from STO to LOAD in Low Power Mode

## 10.4. DCDC Conversion Efficiency From STO to LOAD in High Power Mode

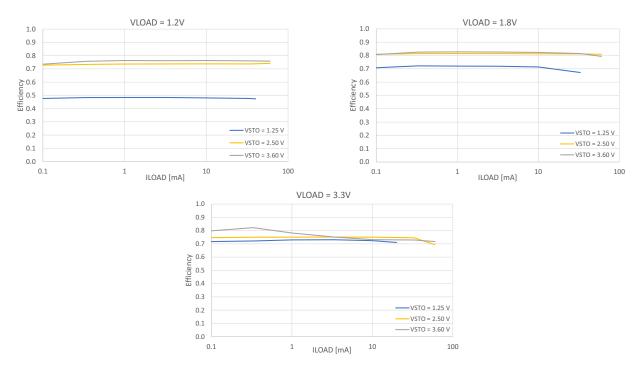


Figure 18: DCDC Efficiency from STO to LOAD in High Power Mode



## 10.5. Quiescent Current

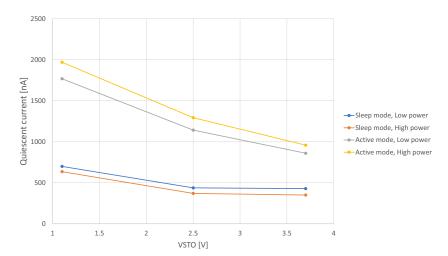


Figure 19: Quiescent Current



## 11. Schematic

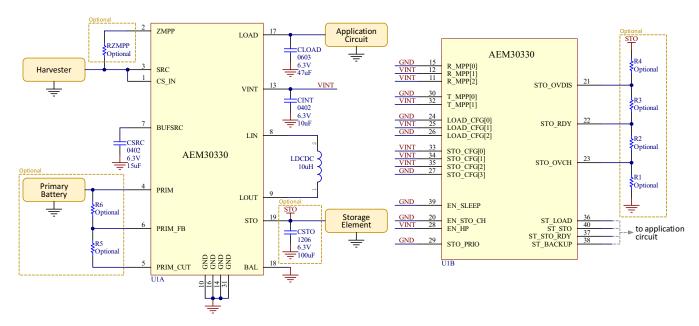


Figure 20: Schematic Example

Designator	Description	Quantity	Manufacturer	Link
U1	AEM30330 - Symbol QFN 40-pin	1	e-peas	order at sales@e-peas.com
LDCDC	Power inductor 10 μH - 1.76A	1	Murata	DFE252010F-100M
CLOAD	Ceramic Cap 47 μF, 6.3V, 20%, X5R 0603	1	Murata	GRM188R60J476ME15
CINT	Ceramic Cap 10 μF, 6.3V, 20%, X5R 0402	1	Murata	GRM155R60J106ME15
CSRC	Ceramic Cap 15 μF, 6.3V, 20%, X5R 0402	1	Murata	GRM155R60J156ME05
CSTO (optional)	Ceramic Cap 100 μF, 6.3V, 20%, X5R 1206	1	TDK	C3216X5R1A107M160AC

Table 13: Minimal Bill of Materials



## 12. Layout

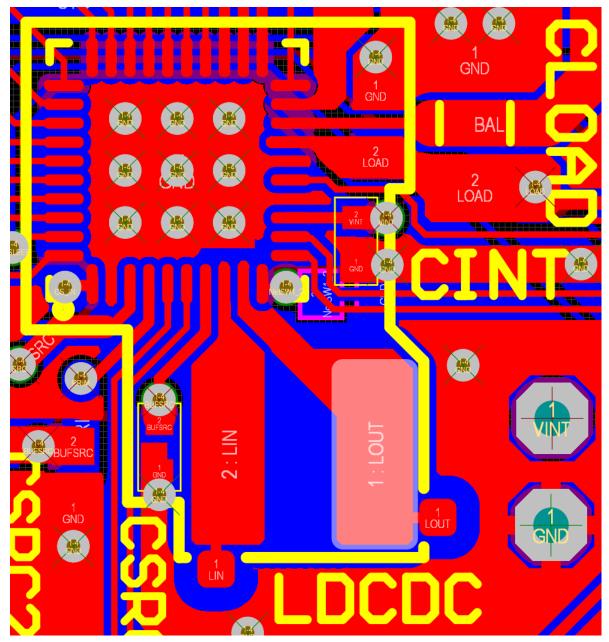


Figure 21: Layout Example for the AEM30330 and its Passive Components

NOTE: schematic, symbol and footprint for the e-peas component can be ordered by contacting e-peas support team at support@e-peas.com



# 13. Package Information

## 13.1. Plastic Quad Flatpack No-Lead (QFN 40-pin 5x5mm)

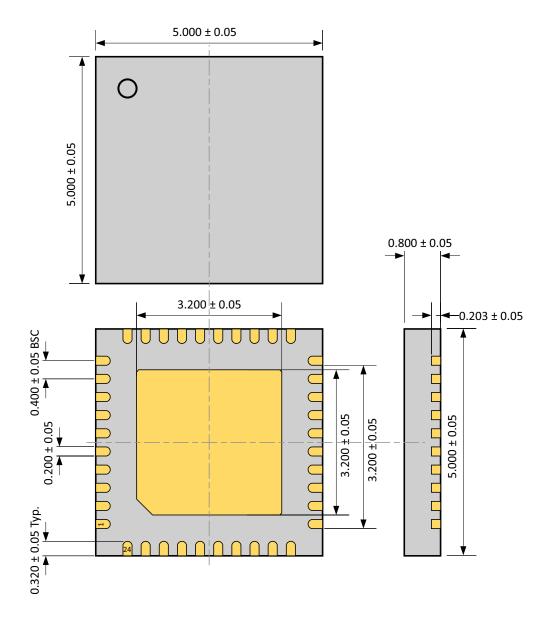


Figure 22: QFN 40-pin 5x5mm Drawing (All Dimensions in mm)



## 13.2. Board Layout

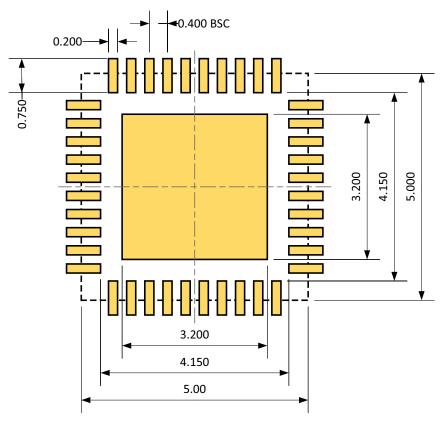


Figure 23: Recommended Board Layout for QFN40 package (All Dimensions in mm)

# 14. Revision History

Revision	Date	Description
0.0	January, 2021	Creation of the document. Preliminary version.
1.0	June, 2021	First version of the document

Table 14: Revision History